

**100V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

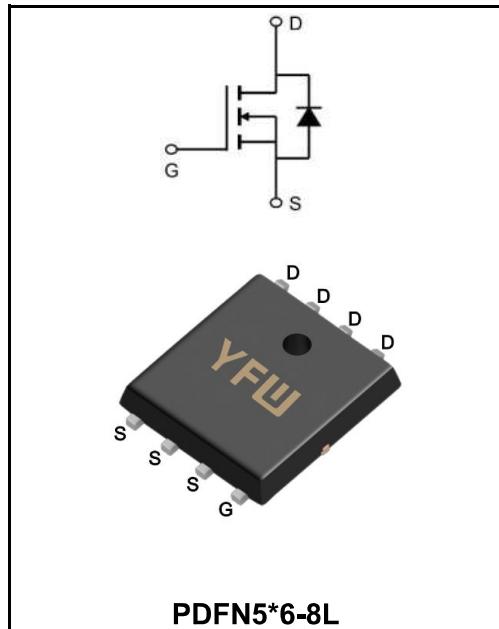
$I_D$	110A
$V_{DSS}$	100V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 6.0mΩ (Type: 4.2 mΩ)

**Features**

- ◆ YFW-SGT technology

**Application**

- ◆ DC/DC Converter
- ◆ LED Backlighting
- ◆ Power Management Switches


**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

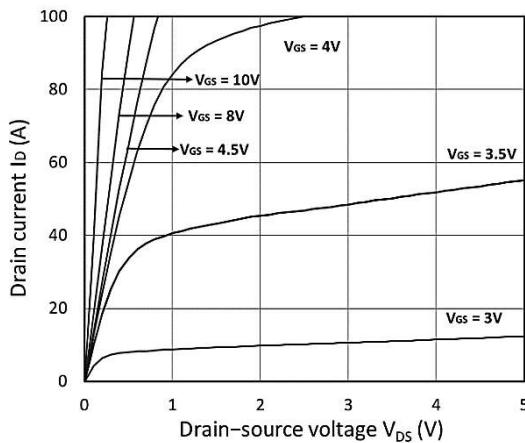
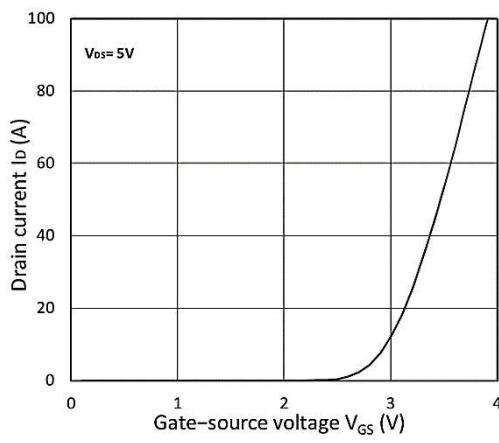
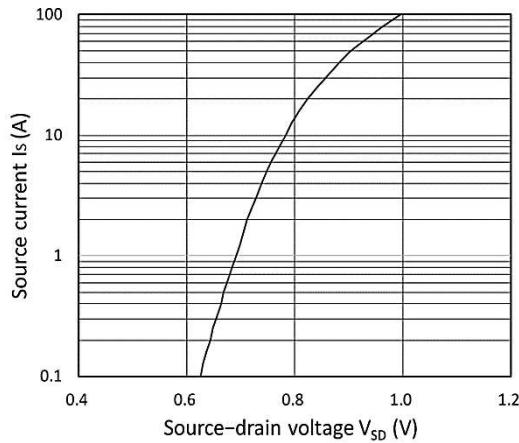
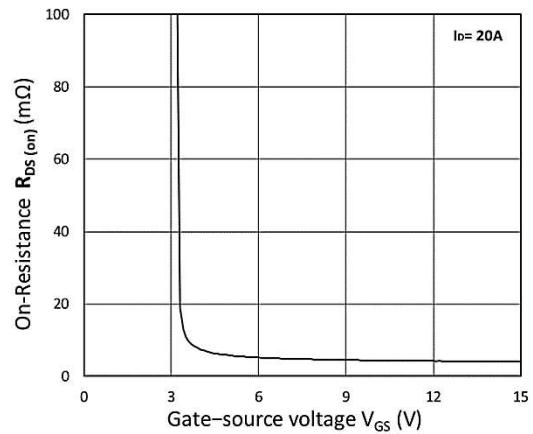
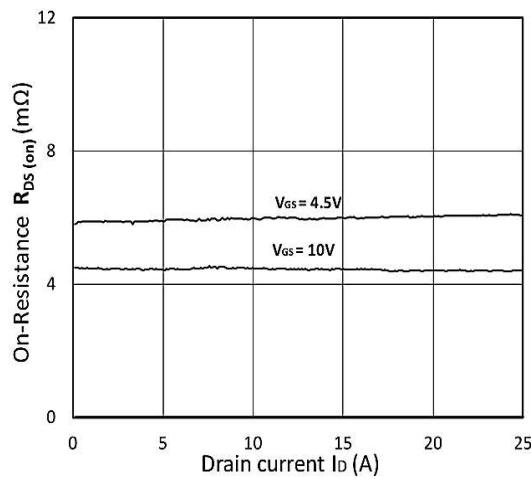
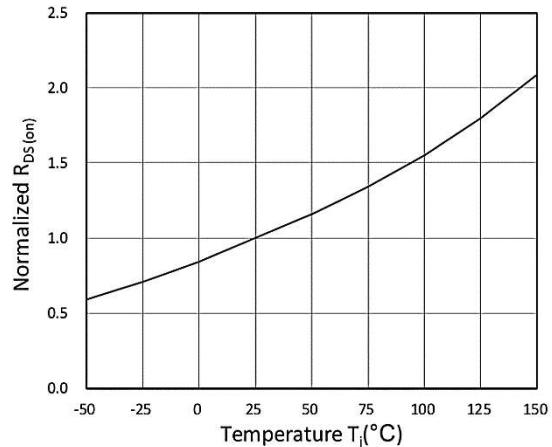
Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $T_c=25^\circ\text{C}$	$I_D$	110	A
Pulsed Drain Current , $T_c=25^\circ\text{C}$	$I_{DM}$	380	A
Power Dissipation @ $T_c=25^\circ\text{C}$	$P_D$	113.6	W
Single Pulse Avalanche Energy <sup>4)</sup>	$E_{AS}$	205	mJ
Operation and storage temperature	$T_{STG}, T_J$	-55 to +150	°C
Thermal Resistance, Junction-case	$R_{\theta JC}$	1.1	°C/W
Thermal Resistance, Junction-ambient <sup>4)</sup>	$R_{\theta JA}$	58	°C/W

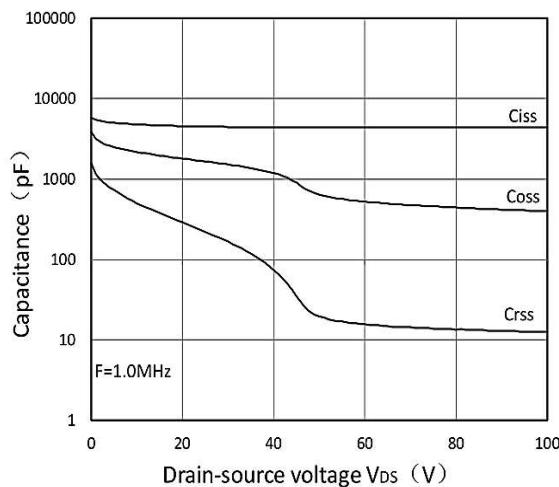
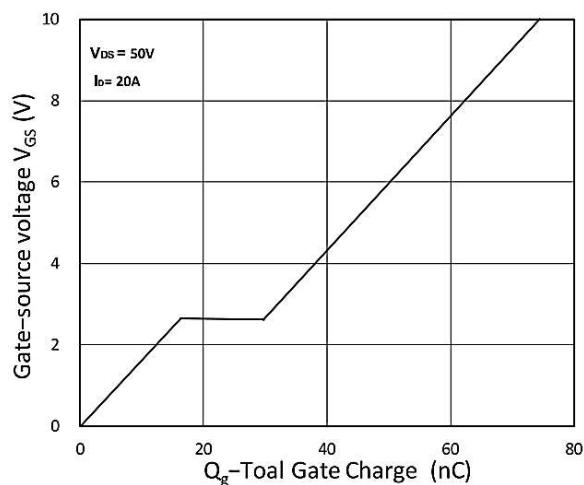
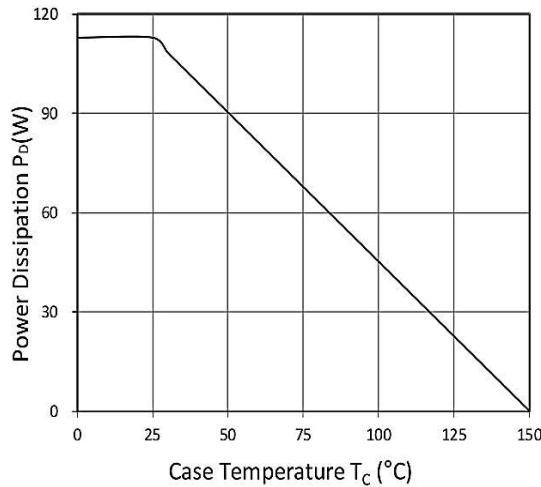
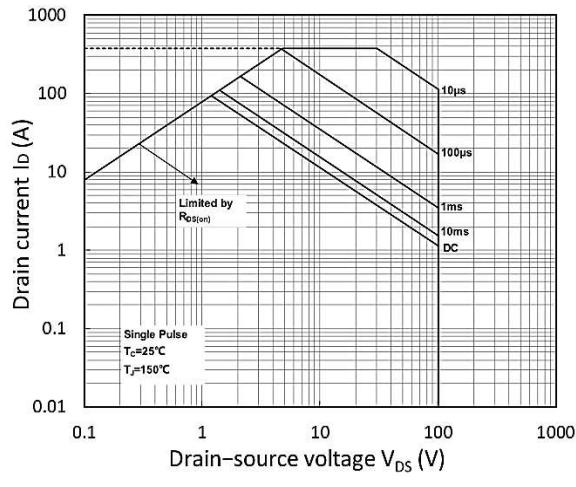
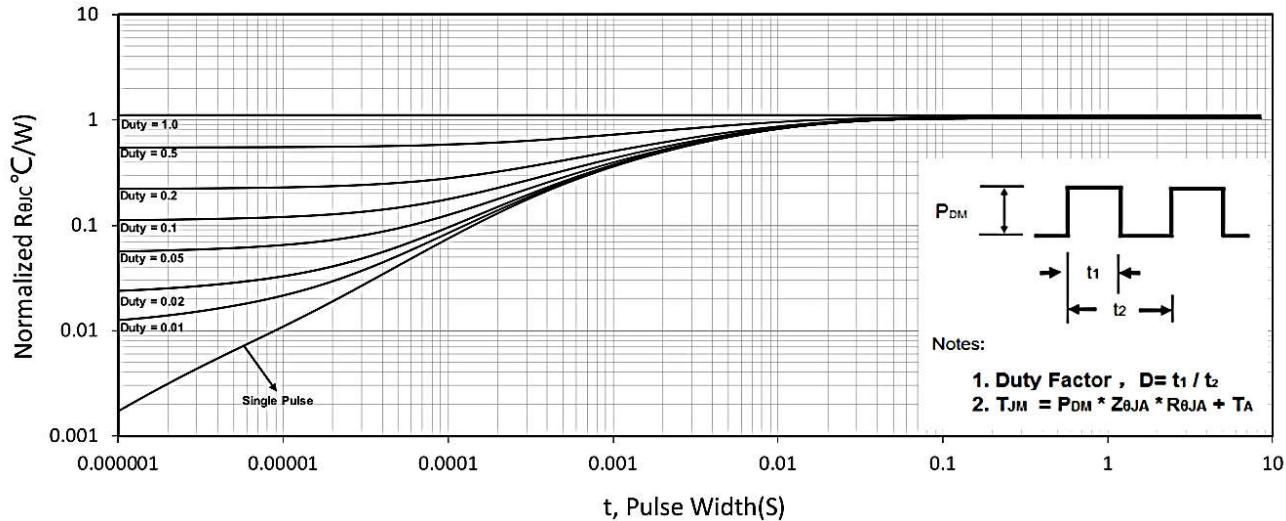
**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	V <sub>DSS</sub>	100	-	-	V
Gate -Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> = 0V, T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =100V, V <sub>GS</sub> = 0V,T <sub>J</sub> =100°C		-	-	100	
Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	V <sub>GS(th)</sub>	1.2	1.8	2.5	V
Drain-Source on-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	R <sub>DS(ON)</sub>	-	4.2	6	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A		-	6.6	9	
Input Capacitance	V <sub>DS</sub> =50V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	4400	-	pF
Output Capacitance		C <sub>oss</sub>	-	645	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	20	-	
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>g</sub>	-	1.7	-	Ω
Total Gate Charge	V <sub>DS</sub> =50V V <sub>GS</sub> =10V I <sub>D</sub> =20A	Q <sub>g</sub>	-	75	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	17	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	13	-	
Turn-on delay time	V <sub>GS</sub> =10V V <sub>DS</sub> =50V R <sub>G</sub> =3Ω I <sub>D</sub> =20A	t <sub>d(on)</sub>	-	15.4	-	ns
Rise Time		T <sub>r</sub>	-	13	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	34	-	
Fall Time		t <sub>f</sub>	-	6.2	-	
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>F</sub> =20A	V <sub>SD</sub>	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	95	A
Body Diode Reverse Recovery Time	I <sub>F</sub> =20A, dI <sub>SD</sub> /dt=100A/μs	t <sub>rr</sub>	-	55	-	ns
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>	-	101	-	

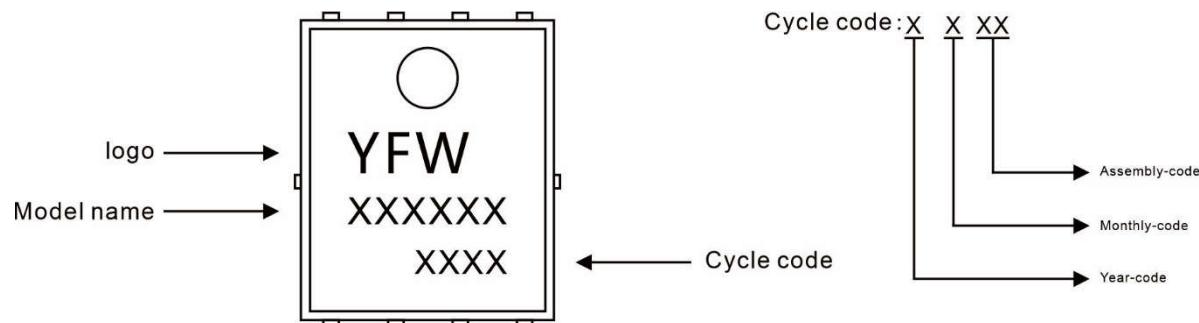
Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=50V, VGS=10V, L=0.4mH, IAS=32A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**

**Figure 1. Output Characteristics**

**Figure 2. Transfer Characteristics**

**Figure 3. Forward Characteristics of Reverse**

**Figure 4. RDS(ON) vs. VGS**

**Figure 5. R DS(ON) vs. ID**

**Figure 6. Normalized R DS(ON) vs. Temperature**

**Ratings and Characteristic Curves**

**Figure 7. Capacitance Characteristics**

**Figure 8. Gate Charge Characteristics**

**Figure 9. Power Dissipation**

**Figure10. Safe Operating Area**

**Figure 11. Normalized Maximum Transient Thermal Impedance**

### Marking Diagram

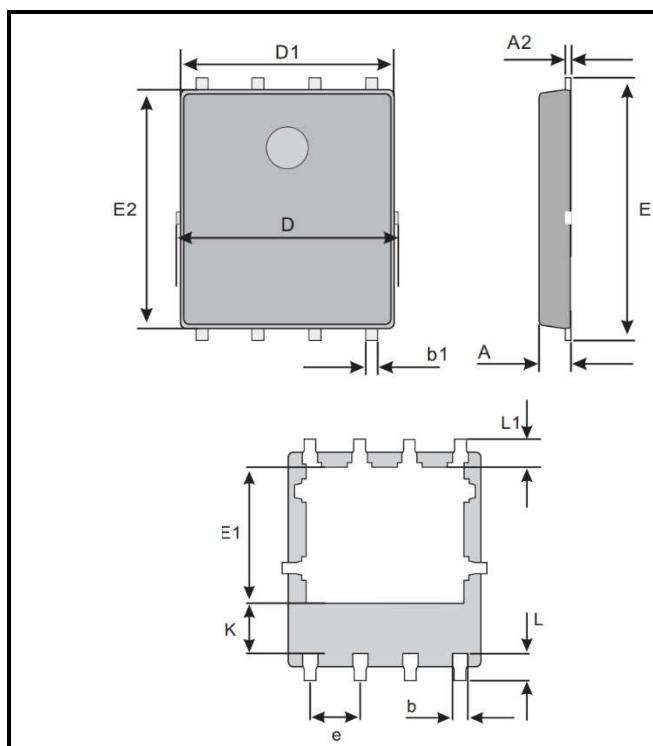


### Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFWG110N10NF	PDFN5*6-8L	0.0032oz(0.093g)	5000pcs/reel	10000pcs/box 50000pcs/Carton

### Package Dimensions

PDFN5\*6-8L



Dim	Millimeter		mil	
	Min.	Max.	Min.	Max.
A	0.9	1.2	35	45
A2	0.204	0.304	8	12
b	0.4ref.		16ref.	
b1	0.2	0.4	8	16
D	5.0	5.3	197	209
D1	4.84	5.24	191	206
E	5.95	6.35	234	250
E1	3.275	3.675	129	145
E2	5.69	6.09	224	232
e	1.27typ.		50typ.	
K	1.29typ.		51typ.	
L	0.585	0.785	23	27
L1	0.7typ.		28typ.	

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